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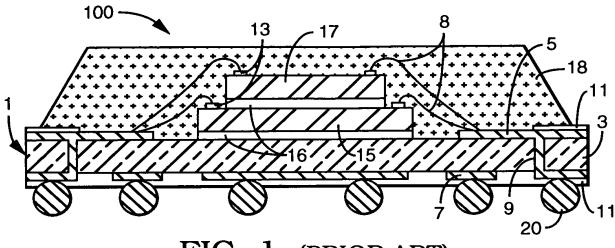
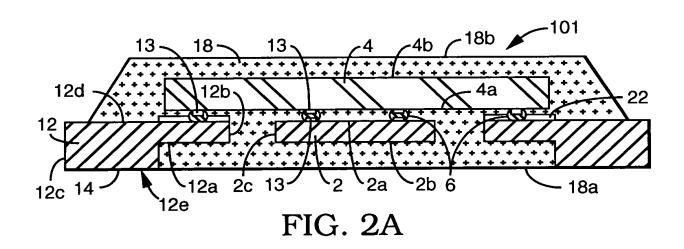


FIG. 1 (PRIOR ART)



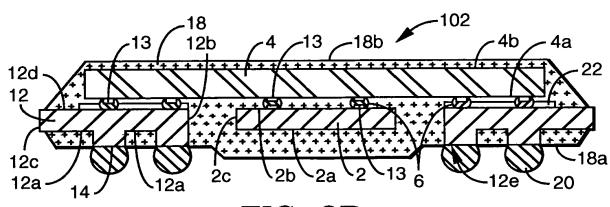
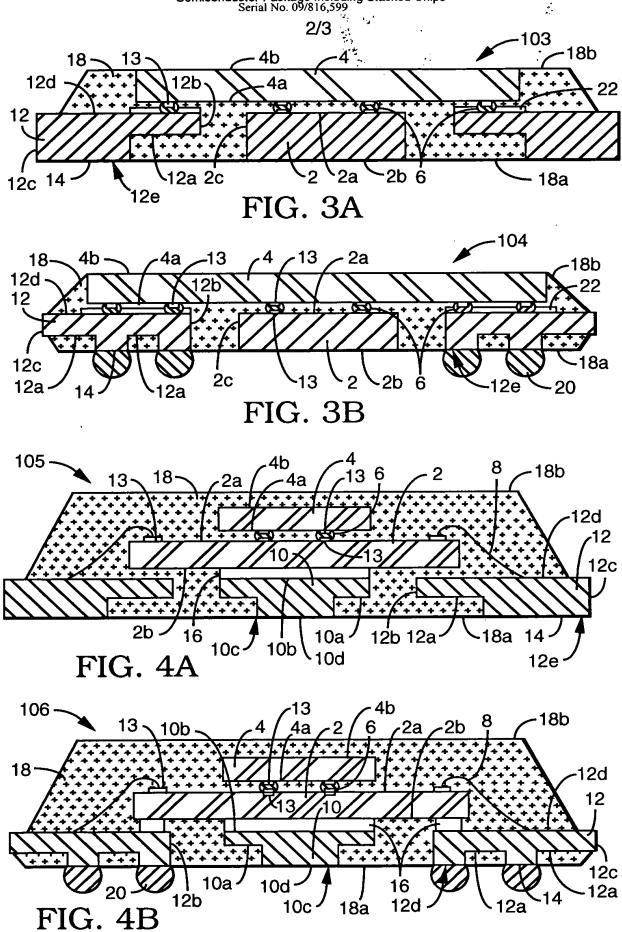


FIG. 2B

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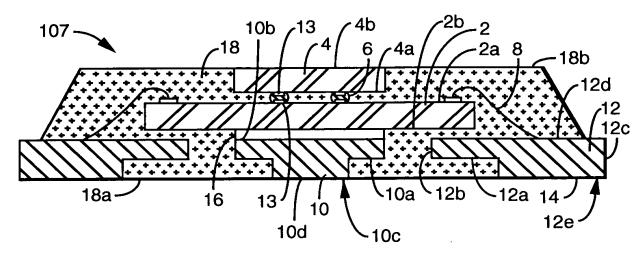


FIG. 5A

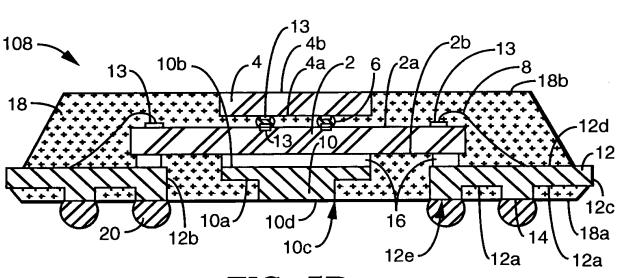


FIG. 5B